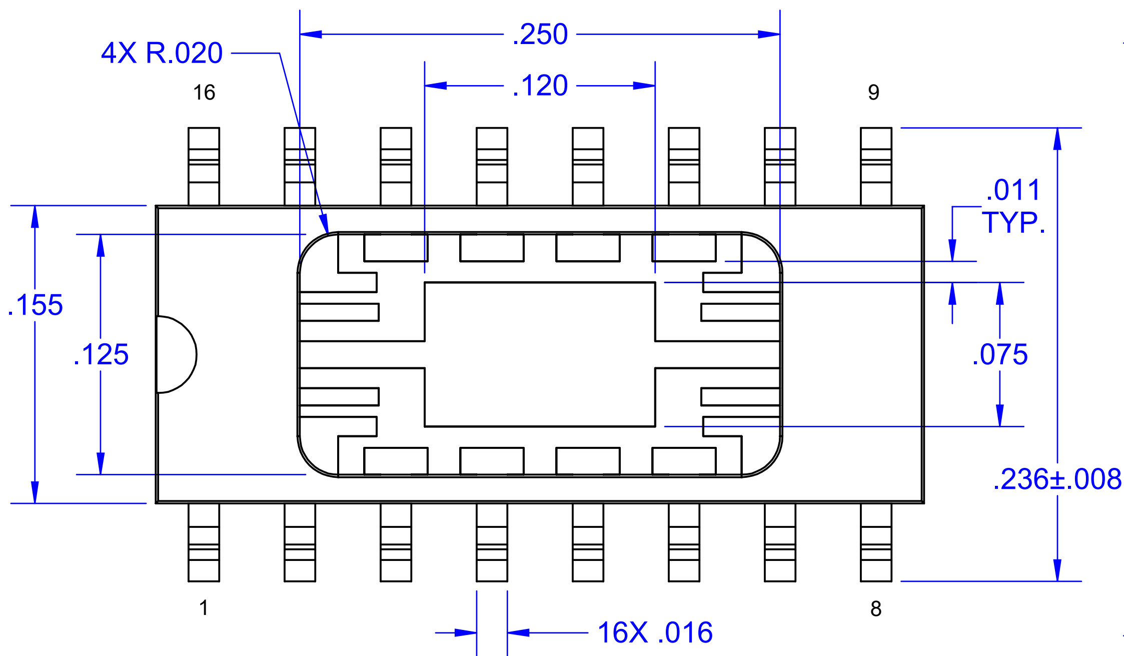
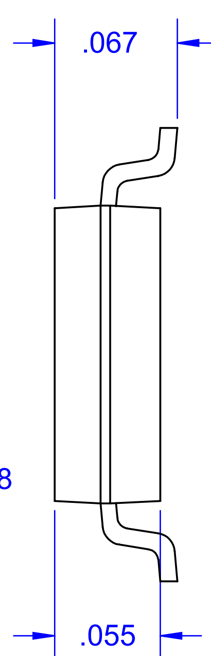
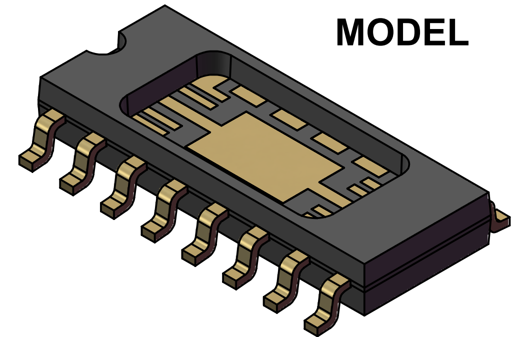
TOP VIEW

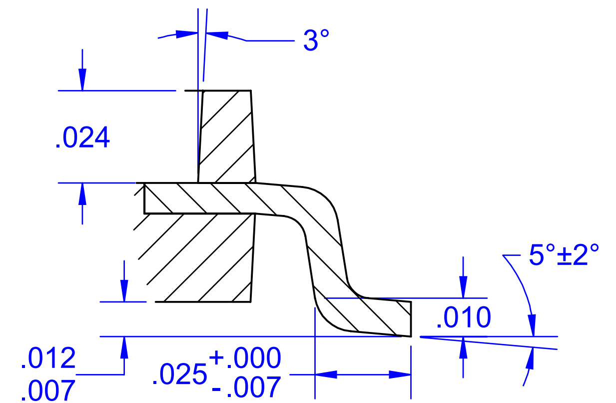


END VIEW



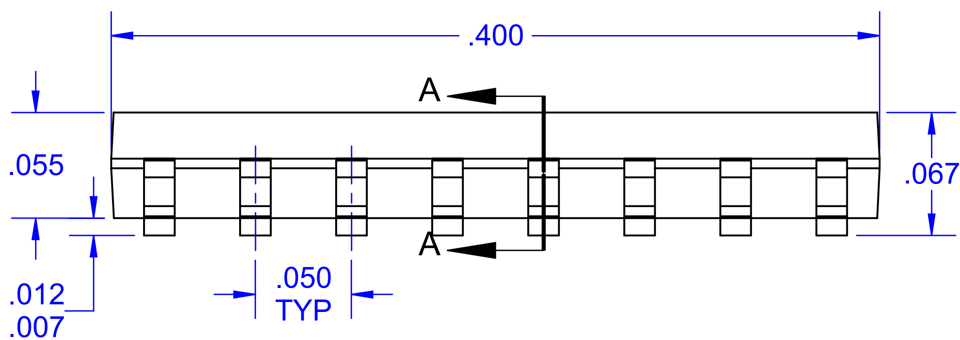
MODEL

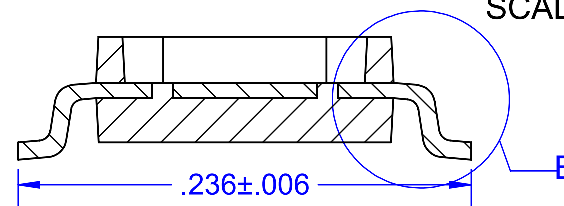




DETAIL B
SCALE 20 : 1

SIDE VIEW

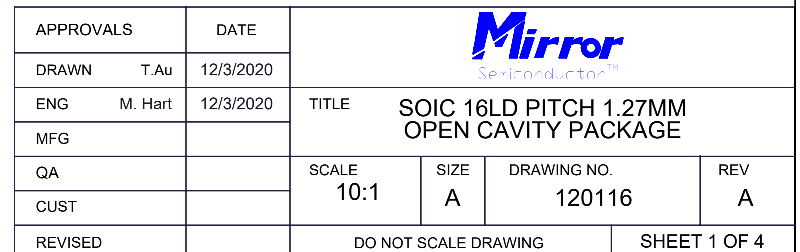




SECTION A-A
SCALE 10 : 1

Notes: (Unless Otherwise Specified).

1) DIMENSIONS: INCHES [MM].
2) PACKAGE CONFORMS TO JEDEC MS-012.
3) BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.
4) LEAD FRAME: COPPER ALLOY A194 FULL HARD.
5) PLATING: NICKEL 100~300 MICROINCHES (2.5~7.6µm) THICK.
   GOLD PLATE 50 MICROINCHES (1.27um) THICK



APPROVALS		DATE	Mirror Semiconductor™			
DRAWN	T.Au	12/3/2020				
ENG	M. Hart	12/3/2020	TITLE	SOIC 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
MFG						
QA			SCALE 10:1	SIZE A	DRAWING NO. 120116	REV A
CUST						
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 4

BOND DIAGRAM

16 15 14 13 12 11 10 9

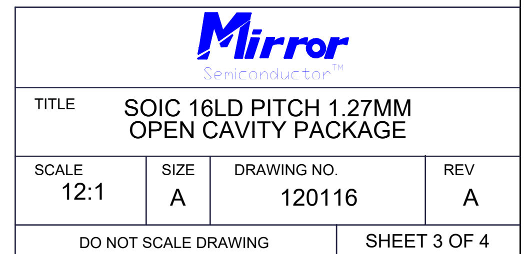
1 2 3 4 5 6 7 8

TITLE	SOIC 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 10:1	SIZE A	DRAWING NO. 120116	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 4	

MODEL

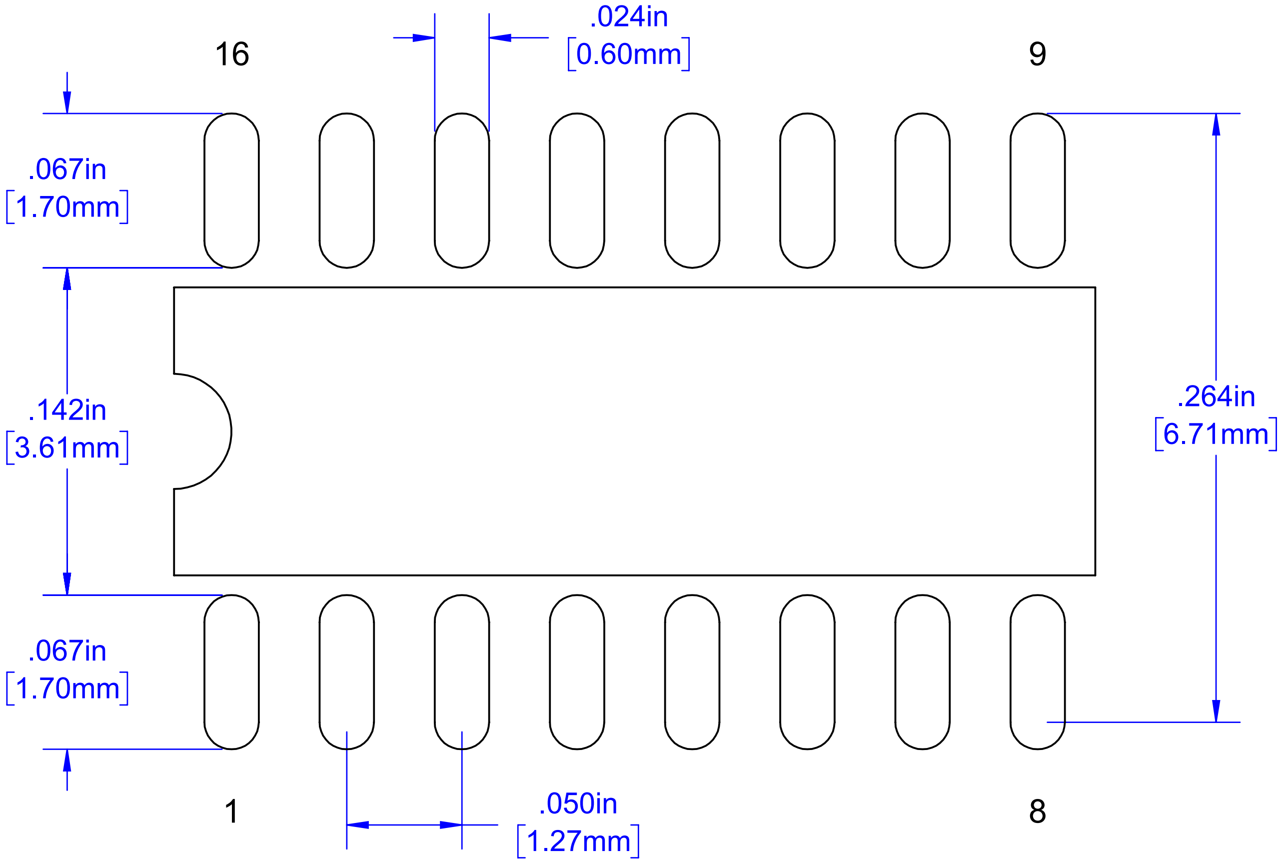
BOTTOM

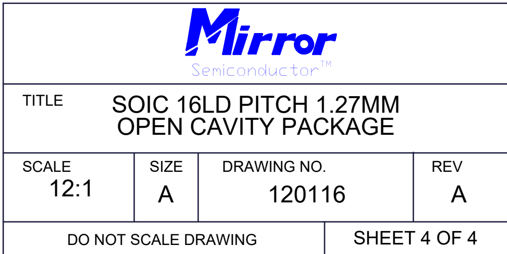
TOP



TITLE	SOIC 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 12:1	SIZE A	DRAWING NO. 120116	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 4	

SUGGESTED PCB LAND PATTERN





TITLE	SOIC 16LD PITCH 1.27MM OPEN CAVITY PACKAGE		
SCALE 12:1	SIZE A	DRAWING NO. 120116	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 4	